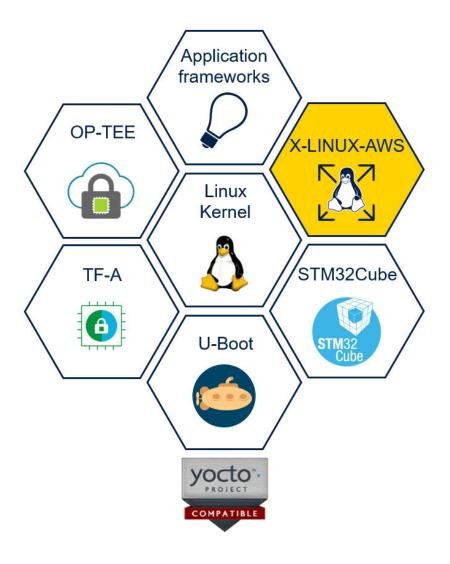


# AWS IoT Greengrass™ Expansion Package for STM32 MPU OpenSTLinux



#### Product status link

X-LINUX-AWS







#### **Features**

- AWS IoT Greengrass<sup>™</sup> V2 integration
- Secured credential storage with one of the following solutions
  - OP-TEE
  - TPM with the X-LINUX-TPM integration
- Application sample based on GTK® to publish and subscribe on MQTT topics
- Compatible with the Yocto Project® build system Scarthgap
- Validated over the OpenSTLinux Distribution v6.0 on STM32MP135F-DK, STM32MP257F-DK, and STM32MP257F-EV1

## **Description**

X-LINUX-AWS is an STM32 MPU OpenSTLinux Expansion Package that targets Amazon Web Services<sup>®</sup> AWS IoT Greengrass<sup>™</sup> V2 for STM32MP13xx and STM32MP25xx microprocessors.

It integrates the Greengrass nucleus component to connect to AWS IoT Core<sup>™</sup> to start and accelerate the development of an IoT solution.

In addition, this OpenSTLinux Expansion Package provides good security practices with the integration of a secure solution for credential storage. This solution is based on the usage of OP-TEE or TPM with X-LINUX-TPM integration.

X-LINUX-AWS includes a demonstration application in which the AWS IoT Greengrass<sup>TM</sup> core device subscribes and publishes on a local MQTT network and on AWS IoT Core<sup>TM</sup>. This is achieved through the component deployment of an MQTT broker and bridge.

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# 1 General information

The X-LINUX-AWS Expansion Package runs on STM32 microprocessors based on Arm® Cortex® processors.

Note: Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.

arm

## 1.1 Ordering information

X-LINUX-AWS is available for free download from the www.st.com website.

## 1.2 Versioning

Since its release v5.1.0, the major and minor versions of the X-LINUX-AWS OpenSTLinux Expansion Package are aligned on the major and minor versions of the OpenSTLinux Distribution. This prevents painful backward compatibility attempts and makes dependencies straightforward.

The X-LINUX-AWS generic versioning vx.y.z is built as follows:

- **x**: major version matching the OpenSTLinux Distribution major version. Each new major version is incompatible with previous OpenSTLinux Distribution versions.
- **y**: minor version matching the OpenSTLinux Distribution minor version. Each new minor version might be incompatible with previous OpenSTLinux Distribution versions.
- z: patch version to introduce bug fixes. A patch version is implemented in a backward-compatible manner.

### 1.3 License

X-LINUX-AWS is delivered under the *Mix Ultimate Liberty+OSS+3rd-party V1* software license agreement (SLA0048).

#### Software component license agreements

The software components provided in this package come with different license schemes. Refer to wiki.st.com/stm32mpu/wiki/X-LINUX-AWS\_licenses for details.

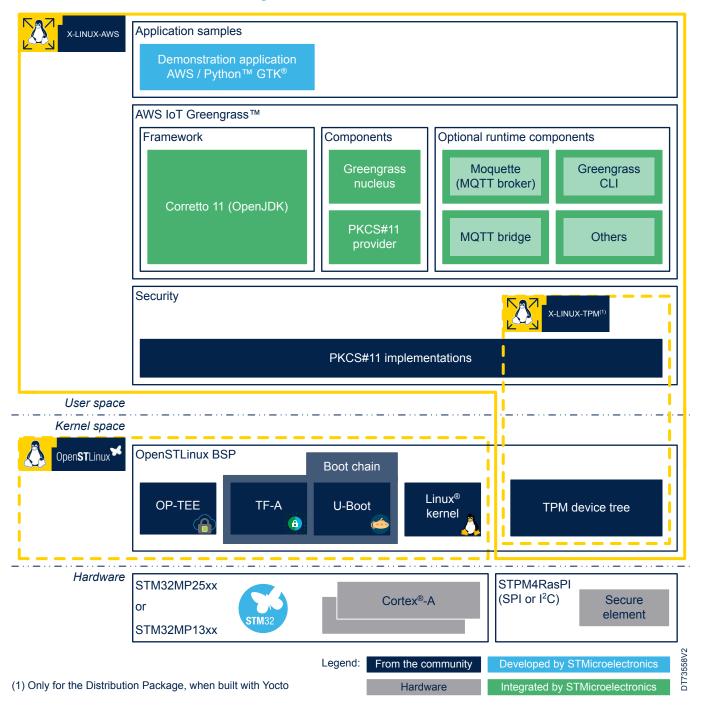
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# 2 Software architecture

The top-level architecture of the X-LINUX-AWS OpenSTLinux Expansion Package is shown in Figure 1.

Figure 1. X-LINUX-AWS architecture



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# **Revision history**

Table 1. Document revision history

Date	Revision	Changes
29-Feb-2024	1	Initial release.
25-Jun-2024	2	Updated:
06-Dec-2024	3	Updated: • Ecosystem 6.0 Added: • Support for STM32MP257F-DK

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